











Monopoli (BA), Italy June 8-9, 2023

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Call for Papers

The IEEE International Workshop on Advances in Sensors and Interfaces (IWASI) is a premier bi-annual workshop on sensors and sensor interfaces that for 20 years has presented advances and disruptive solutions in the fields of software, architecture, design, manufacturing and materials for sensors and integrated circuits.

The 9th edition of the IEEE IWASI focuses on modelling, analysis, design and development of embedded cyber-physical systems, sensors and actuators for personalized medicine and healthcare applications, machine learning for low power embedded systems and smart sensing applications, high-energy physics, chemical sensing, autonomous sensors and interfaces, hard- and software co-design for security and cryptography, autonomous driving and security for airplanes and trains.

Topics

Papers are solicited in – but are not limited to - the following topics:

- Sensors and actuators for personalized medicine and healthcare applications
- Brain Computer Interfaces: from algorithm to the implementation
- Remote sensing applications for environmental control
- · Sensor systems for Robotics and Industry 4.0
- Smart sensors and devices for Artificial Intelligence
- Sensor systems for autonomous driving in railway and automotive
- Embedded Sensor Systems for near-sensor computing
- · High-energy physics
- Ultra-low power communication devices for sensor networks
- Biochemical sensors, labs on a chip, multi-electrode arrays and their interfaces
- Sensor interfaces: analog and digital sensor data processing architectures and ICs
- Novel testing and modeling techniques for sensors systems
- Printed, flexible, biodegradable and biocompatible sensors and interfaces
- New materials and new technologies for sensors, including 1D and 2D materials
- 3D materials and techniques for sensing-oriented additive manufacturing.
- Energy harvesters and self-powered sensors for portable and smart electronics
- Label-Free sensors for biomedical and environmental monitoring

Accepted papers will be included in the workshop proceedings and available on IEEEXplore.

| Paper Submission | Author Notification | Camera-Ready |
|------------------|---------------------|----------------|
| March 1, 2023 | March 10, 2023 | April 30, 2023 |

Submissions

Papers must be submitted in PDF format following the IEEE template. They must be double column and should not exceed **six A4 pages**. Manuscript guidelines and authors instructions are available on the conference web site.

Selected papers will be invited to submit an extended version for publication in prestigious IEEE journal.

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